

C1210X279B2TAC7210

SMD Comm X8G HT150C Flex, Ceramic, 2.7 pF, ± 0.1 pF, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



Click [here](#) for the 3D model.

General Information

Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	30 mg
Shelf Life	78 Weeks
MSL	1

Dimensions

Chip Size	1210
L	3.3mm ± 0.4 mm
W	2.6mm ± 0.3 mm
T	0.78mm ± 0.20 mm
S	1.5mm MIN
B	0.6mm ± 0.25 mm

Packaging Specifications

Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	10000

Specifications

Capacitance	2.7 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	± 0.1 pF
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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